- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

The '279 offers 4 basic $\overline{S} \cdot \overline{R}$ flip-flop latches in one 16-pin, 300-mil package. Under conventional operation, the $\overline{S} \cdot \overline{R}$ inputs are normally held high. When the \overline{S} input is pulsed low, the Ω output will be set high. When \overline{R} is pulsed low, the Ω output will be reset low. Normally, the $\overline{S} \cdot \overline{R}$ inputs should not be taken low simultaneously. The Ω output will be unpredictable in this condition.

FUNCTION TABLE (each latch)

INP	UTS	OUTPUT
St	R	a
н	Н	α ₀
L	Н	н
н	L	L
L	L	H [‡]
l .		

H = high level

L = low level

†For latches with double S inputs:

 Ω_0 = the level of Ω before the indicated input conditions were established.

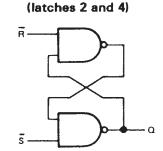
 $H = both \overline{S}$ inputs high

L = one or both \$\overline{S}\$ inputs low

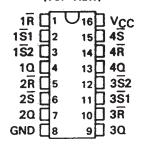
logic diagram (positive logic)

\$1 0 0

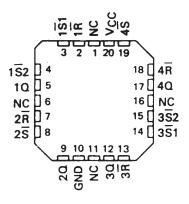
(latches 1 and 3)



SN54279, SN54LS279A . . . J OR W PACKAGE SN74279 . . . N PACKAGE SN74LS279A . . . D OR N PACKAGE (TOP VIEW)

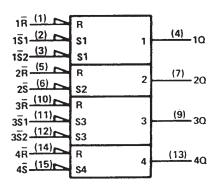


SN54LS279A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic symbol§



[§]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

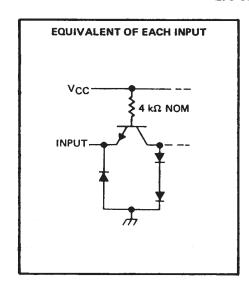
Pin numbers shown are for D, J, N, and W packages.

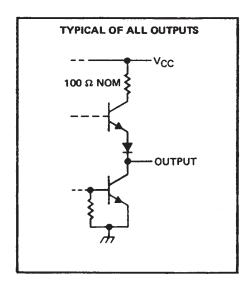
 $^{^\}ddagger$ This configuration is nonstable: that is, it may not persist when the \overline{S} and \overline{R} inputs return to their inactive (high) level.

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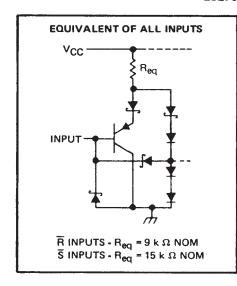
schematics of inputs and outputs

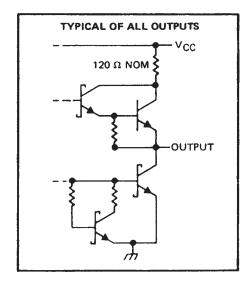
'279 CIRCUITS





'LS279A CIRCUITS





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage: '279	5.5 V
' LS279A	7 V
Operating free-air temperature range: SN54' TYPES	55° C to 125° C
SN74' TYPES	0° C to 70° C
Storage temperature range	65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.



recommended operating conditions

			SN5427	9		SN74279			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage	2			2			V	
VIL	Low-level input voltage			0.8			0.8	V	
Юн	High-level output current			- 0.8			- 0.8	mA	
IOL	Low-level output current			16			16	mA	
tw	Pulse duration, low	20			20			ns	
TA	Operating free-air temperature	- 55		125	0		70	°C	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDIT	noue†		SN5427	9		SN7427	9	UNIT
FANAME (Ch		1621 COMDIT	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNII	
VIK	VCC = MIN,	I _I = - 12 mA				– 1.5			- 1.5	V
Voн	V _{CC} = MIN,	V _{IL} = 0.8 V,	1 _{OH} = - 0.8 mA	2.4	3.4		2.4	3.4		V
VOL	V _{CC} = MIN,	V _{1H} = 2 V,	1 _{OL} = 16 mA		0.2	0.4		0.2	0.4	V
11	V _{CC} = MAX,	V _I = 5.5 V				1			1	mA
Чн	V _{CC} = MAX,	V ₁ = 2.4 V				40			40	μΑ
IIL	V _{CC} = MAX,	V ₁ = 0.4 V				- 1.6			- 1.6	mA
I _{OS} \$	V _{CC} = MAX			- 18		- 55	- 18		- 57	mA
1cc	V _{CC} = MAX,	See Note 2			18	30		18	30	mΑ

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: I_{CC} is measured with all R inputs grounded, all S inputs at 4.5 V, and all outputs open.

switching characteristics, VCC = 5 V, TA = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	IDITIONS	MIN	TYP	MAX	UNIT
^t PLH	<u>-</u>					12	22	ns
^t PHL	3		$R_L = 400 \Omega$,	C ₁ = 15 pF		9	15	113
^t PHL	Ř	Q				15	27	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

^{\$} All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{C}$.

Not more than one output should be shorted at a time.

SN54279, SN54LS279A, SN74279, SN74LS279A QUADRUPLE \overline{S} - \overline{R} LATCHES

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recommended operating conditions

		sı	154LS27	79A	SA	174LS27	79A	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
Іон	High-level output current			0.4			- 0.4	mA
IOL	Low-level output current			4			8	mΑ
t _W	Pulse duration, low	20			20			ns
TA	Operating free-air temperature	– 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

BADAMETED		TEST CONDIT	rougt	Si	154LS27	79A	SN	174LS27	79A	UNIT
PARAMETER		1EST CONDIT	IONS	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN,	I _I = - 18 mA				1.5			- 1.5	V
Voн	V _{CC} = MIN,	VIL = MAX,	I _{OH} = 0.4 mA	2.5	3.4		2.7	3.4		V
V	V _{CC} = MIN,	V _{IH} = 2 V,	IOL = 4 mA		0.25	0.4		0.25	0.4	V
VOL	V _{CC} = MIN,	V _{1H} = 2 V,	IOL = 8 mA					0.25	0.5	v
11	V _{CC} = MAX,	V ₁ = 7 V				0.1			0.1	mΑ
ΊΗ	V _{CC} = MAX,	V ₁ = 2.7 V				20			20	μΑ
IIL	V _{CC} = MAX,	V ₁ = 0.4 V				- 0.2			- 0.2	mA
I _{OS} §	V _{CC} = MAX			- 20		- 100	- 20		- 100	mA
¹cc	V _{CC} = MAX,	See note 2			3.8	7		3.8	7	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 2: I_{CC} is measured with all R inputs grounded, all S inputs at 4.5 V, and all outputs open.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST COM	NDITIONS	MIN	TYP	MAX	UNIT
^t PLH	_	0				12	22	ns
^t PHL	3	· ·	$R_L = 2 k\Omega$,	C _L = 15 pF		13	21	113
tPHL	Ā	Q				15	27	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{C}$.

[§] Not more than one output should be shorted at a time, and the duration of the short-circuit should be less than one second.



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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
76018012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	76018012A SNJ54LS 279AFK	Samples
7601801EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7601801EA SNJ54LS279AJ	Samples
7601801EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7601801EA SNJ54LS279AJ	Samples
7601801FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7601801FA SNJ54LS279AW	Samples
7601801FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7601801FA SNJ54LS279AW	Samples
SN54LS279AJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS279AJ	Samples
SN54LS279AJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS279AJ	Samples
SN74LS279AD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS279A	Samples
SN74LS279AD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS279A	Samples
SN74LS279ADE4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS279A	Samples
SN74LS279ADE4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS279A	Samples
SN74LS279ADR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS279A	Samples
SN74LS279ADR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS279A	Samples
SN74LS279AN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS279AN	Samples
SN74LS279AN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS279AN	Samples
SN74LS279ANE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS279AN	Samples
SN74LS279ANE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS279AN	Samples
SN74LS279ANSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS279A	Samples



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Orderable Device	Status	Package Type	Package Drawing		Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS279ANSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS279A	Samples
SNJ54LS279AFK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	76018012A SNJ54LS 279AFK	Samples
SNJ54LS279AFK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	76018012A SNJ54LS 279AFK	Samples
SNJ54LS279AJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7601801EA SNJ54LS279AJ	Samples
SNJ54LS279AJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7601801EA SNJ54LS279AJ	Samples
SNJ54LS279AW	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7601801FA SNJ54LS279AW	Samples
SNJ54LS279AW	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7601801FA SNJ54LS279AW	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

PACKAGE OPTION ADDENDUM

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(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS279A, SN74LS279A:

Catalog: SN74LS279A

Military: SN54LS279A

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS279ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS279ANSR	so	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS279ADR	SOIC	D	16	2500	340.5	336.1	32.0
SN74LS279ANSR	SO	NS	16	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
76018012A	FK	LCCC	20	1	506.98	12.06	2030	NA
7601801FA	W	CFP	16	1	506.98	26.16	6220	NA
SN74LS279AD	D	SOIC	16	40	507	8	3940	4.32
SN74LS279ADE4	D	SOIC	16	40	507	8	3940	4.32
SN74LS279AN	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS279AN	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS279ANE4	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS279ANE4	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54LS279AFK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ54LS279AW	W	CFP	16	1	506.98	26.16	6220	NA



SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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